

**IPC J-STD-004B**  
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# ***JOINT INDUSTRY STANDARD***

Requirements for  
Soldering Fluxes



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IPC J-STD-004B with Amendment 1

# Requirements for Soldering Fluxes

A standard developed by the Flux Specifications Task Group (5-24a)  
of the Assembly and Joining Processes Committee (5-20) of IPC

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Users of this publication are encouraged to participate in the  
development of future revisions.

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